

## STM706T/S/R, STM706P, STM708T/S/R

### 3 V supervisor

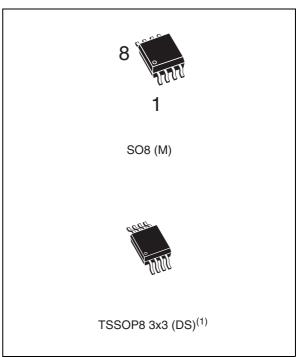
#### Datasheet -production data

#### **Features**

- Precision V<sub>CC</sub> monitor
  - $\quad T: 3.00 \ V \ \leq V_{RST} \ \leq 3.15 \ V$
  - S: 2.88 V  $\leq$  V<sub>RST</sub>  $\leq$  3.00 V
  - R: STM706P: 2.59 V  $\leq$  V<sub>RST</sub>  $\leq$  2.70 V
- RST and RST outputs
- 200 ms (typ.) t<sub>rec</sub>
- Watchdog timer 1.6 s (typ.)
- Manual reset input (MR)
- Power-fail comparator (PFI/PFO)
- Low supply current 40 µA (typ.)
- Guaranteed RST (RST) assertion down to V<sub>CC</sub> = 1.0 V
- Operating temperature: -40 °C to 85 °C (industrial grade)
- RoHS compliance
  - Lead-free components are compliant with the RoHS directive

### **Applications**

- Computers
- Controllers
- Intelligent instruments



- 1. Contact local ST sales office for availability.
- Critical µP power monitoring
- Terminals
- Base stations
- Medical equipment
- Set-top box

Table 1. Device summary

	Watchdog input	Watchdog output <sup>(1)</sup>	Active low RST <sup>(1)</sup>	Active high RST <sup>(1)</sup>	Manual reset input	Power-fail comparator
STM706T/S/R	✓	✓	✓		✓	✓
STM706P <sup>(2)</sup>	✓	✓		✓	✓	✓
STM708T/S/R			✓	✓	✓	✓

<sup>1.</sup> Push-pull output.

2. The STM706P device is identical to the STM706R device, except its reset output is active high.

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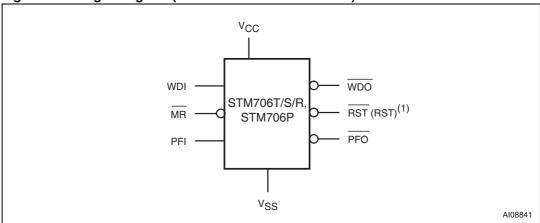
### 1 Description

The STM70x supervisors are self-contained devices which provide microprocessor supervisory functions. A precision voltage reference and comparator monitors the  $V_{CC}$  input for an out-of-tolerance condition. When an invalid  $V_{CC}$  condition occurs, the reset output  $(\overline{RST})$  is forced low (or high in the case of RST).

These devices also offer a watchdog timer (except for STM708T/S/R) as well as a power-fail comparator to provide the system with an early warning of impending power failure.

The STM706P device is identical to the STM706R device, except its reset output is active high. These devices are available in a standard 8-pin SOIC package or a space-saving 8-pin TSSOP package.

Figure 1. Logic diagram (STM706T/S/R and STM706P)



1. For STM706P only.

Figure 2. Logic diagram (STM708T/S/R)

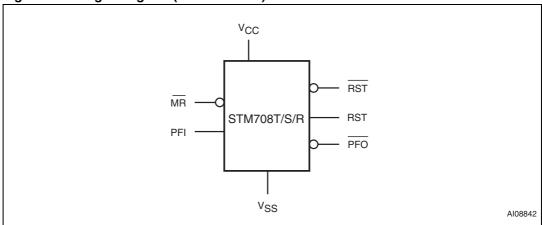
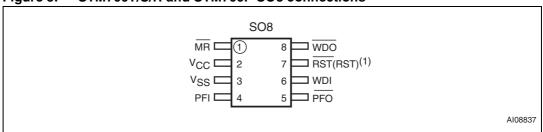


Table 2. Signal names

Symbol	Name
MR	Push-button reset input
WDI	Watchdog input
WDO	Watchdog output
RST	Active low reset output
RST <sup>(1)</sup>	Active high reset output
V <sub>CC</sub>	Supply voltage
PFI	Power-fail input
PFO	Power-fail output
V <sub>SS</sub>	Ground
NC	No connect

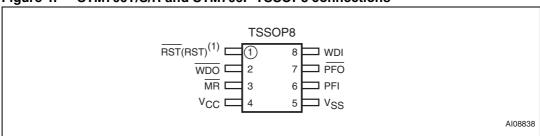
<sup>1.</sup> For STM706P and STM708T/S/R only.

Figure 3. STM706T/S/R and STM706P SO8 connections



1. For STM706P reset output is active high.

Figure 4. STM706T/S/R and STM706P TSSOP8 connections



1. For STM706P reset output is active high.

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Figure 5. STM708T/S/R SO8 connections

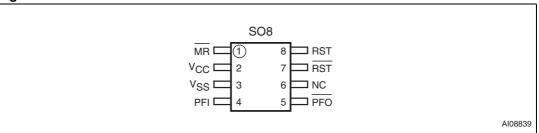
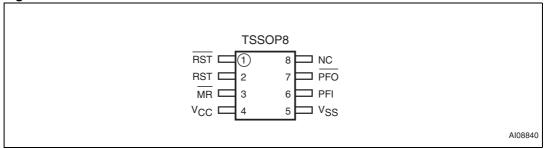


Figure 6. STM708T/S/R TSSOP8 connections



### 2 Pin descriptions

#### 2.1 MR

A logic low on  $\overline{\text{MR}}$  asserts the reset output. Reset remains asserted as long as  $\overline{\text{MR}}$  is low and for  $t_{\text{rec}}$  after  $\overline{\text{MR}}$  returns high. This active low input has an internal pull-up. It can be driven from a TTL or CMOS logic line, or shorted to ground with a switch. Leave open if unused.

#### 2.2 WDI

If WDI remains high or low for 1.6 s, the internal watchdog timer runs out and reset (or  $\overline{\text{WDO}}$ ) is triggered. The internal watchdog timer clears while reset is asserted or when WDI sees a rising or falling edge.

The watchdog function can be disabled by allowing the WDI pin to float.

#### 2.3 WDO

 $\overline{\text{WDO}}$  goes low when a transition does not occur on WDI within 1.6 s, and remains low until a transition occurs on WDI (indicating the watchdog interrupt has been serviced) or  $\overline{\text{MR}}$  input is asserted (goes low).  $\overline{\text{WDO}}$  also goes low when  $V_{CC}$  falls below the reset threshold; however, unlike the reset output,  $\overline{\text{WDO}}$  goes high as soon as  $V_{CC}$  exceeds the reset threshold. Output type is push-pull.

Note:

For those devices with a  $\overline{WDO}$  output, a watchdog timeout will not trigger reset unless  $\overline{WDO}$  is connected to  $\overline{MR}$ .

#### 2.4 **RST**

Pulses low for  $t_{rec}$  when triggered, and stays low whenever  $V_{CC}$  is below the reset threshold or when  $\overline{MR}$  is a logic low. It remains low for  $t_{rec}$  after either  $V_{CC}$  rises above the reset threshold, the watchdog triggers a reset, or  $\overline{MR}$  goes from low to high.

#### 2.5 RST

Pulses high for  $t_{rec}$  when triggered, and stays high whenever  $V_{CC}$  is above the reset threshold or when  $\overline{MR}$  is a logic high. It remains high for  $t_{rec}$  after either  $V_{CC}$  falls below the reset threshold, the watchdog triggers a reset, or  $\overline{MR}$  goes from high to low.

#### 2.6 PFI

When PFI is less than  $V_{PFI}$ ,  $\overline{PFO}$  goes low; otherwise,  $\overline{PFO}$  remains high. Connect to ground if unused.

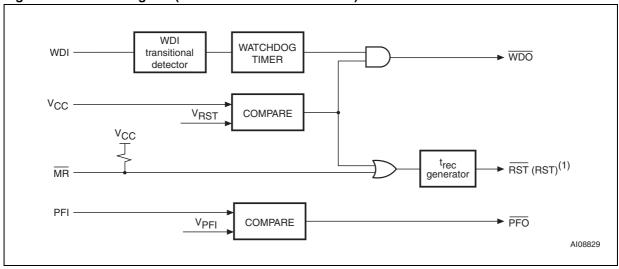
### 2.7 **PFO**

When PFI is less than  $V_{PFI}$ ,  $\overline{PFO}$  goes low; otherwise,  $\overline{PFO}$  remains high. Output type is push-pull.  $\overline{PFO}$  pin is not supposed to be forced low by a processor.  $\overline{MR}$  input is gated off during the period  $\overline{PFO}$  is forced low. Leave open if unused.

Table 3. Pin description

		Р	in				
STM	STM706P		06T/S/R	STM708T/S/R		Name	Function
SO8	TSSOP8	SO8	TSSOP8	SO8	TSSOP8		
1	3	1	3	1	3	MR	Push-button reset input
6	8	6	8	_	_	WDI	Watchdog input
8	2	8	2	_	_	WDO	Watchdog output (push-pull)
_	_	7	1	7	1	RST	Active low reset output
7	1	_	_	8	2	RST	Active high reset output
2	4	2	4	2	4	V <sub>CC</sub>	Supply voltage
4	6	4	6	4	6	PFI	Power-fail input
5	7	5	7	5	7	PFO	Power-fail output (push-pull)
3	5	3	5	3	5	V <sub>SS</sub>	Ground
_	_	_	_	6	8	NC	No connect

Figure 7. Block diagram (STM706T/S/R and STM706P)



1. For STM706P only.

Figure 8. Block diagram (STM708T/S/R)

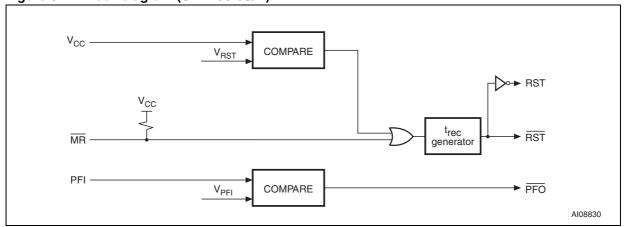
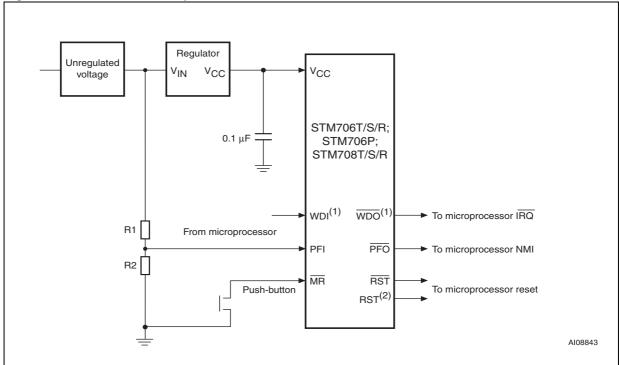


Figure 9. Hardware hookup



- 1. For STM706T/S/R and STM706P devices.
- 2. For STM706P and STM708T/S/R devices.

### 3 Operation

#### 3.1 Reset output

The STM70x supervisor asserts a reset signal to the MCU whenever  $V_{CC}$  goes below the reset threshold ( $V_{RST}$ ), a watchdog timeout occurs (if  $\overline{WDO}$  is connected to  $\overline{MR}$ ), or when the push-button reset input ( $\overline{MR}$ ) is taken low.  $\overline{RST}$  is guaranteed to be a logic low (logic high for STM706P and STM708T/S/R) for  $V_{CC} < V_{RST}$  down to  $V_{CC} = 1$  V for  $T_A = 0$  °C to 85 °C.

During power-up, once  $V_{CC}$  exceeds the reset threshold an internal timer keeps  $\overline{RST}$  low for the reset timeout period,  $t_{rec}$ . After this interval  $\overline{RST}$  returns high.

If  $V_{CC}$  drops below the reset threshold,  $\overline{RST}$  goes low. Each time  $\overline{RST}$  is asserted, it stays low for at least the reset timeout period ( $t_{rec}$ ). Any time  $V_{CC}$  goes below the reset threshold the internal timer clears. The reset timer starts when  $V_{CC}$  returns above the reset threshold.

#### 3.2 Push-button reset input

A logic low on  $\overline{MR}$  asserts reset. Reset remains asserted while  $\overline{MR}$  is low, and for  $t_{rec}$  (see Figure 27) after it returns high. The  $\overline{MR}$  input has an internal 40 k $\Omega$  pull-up resistor, allowing it to be left open if not used. This input can be driven with TTL/CMOS-logic levels or with open-drain / collector outputs. Connect a normally open momentary switch from  $\overline{MR}$  to GND to create a manual reset function; external debounce circuitry is not required. If  $\overline{MR}$  is driven from long cables or the device is used in a noisy environment, connect a 0.1  $\mu$ F capacitor from  $\overline{MR}$  to GND to provide additional noise immunity.  $\overline{MR}$  may float, or be tied to  $V_{CC}$  when not used.

### 3.3 Watchdog input (STM706T/S/R and STM706P)

The watchdog timer can be used to detect an out-of-control MCU. If the MCU does not toggle the watchdog input (WDI) within  $t_{WD}$  (1.6 s), the watchdog output pin (WDO) is asserted. The internal 1.6s timer is cleared by either:

- 1. a reset pulse, or
- 2. by toggling WDI (high-to-low or low-to-high), which can detect pulses as short as 50 ns.

See Figure 28 for STM706T/S/R and STM706P.

The timer remains cleared and does not count for as long as reset is asserted. As soon as reset is released, the timer starts counting.

Note:

The watchdog function may be disabled by floating WDI or tri-stating the driver connected to WDI. When tri-stated or disconnected, the maximum allowable leakage current is 10 µA and the maximum allowable load capacitance is 200 pF.

### 3.4 Watchdog output (STM706T/S/R and STM706P)

When  $V_{CC}$  drops below the reset threshold,  $\overline{WDO}$  will go low even if the watchdog timer has not yet timed out. However, unlike the reset output,  $\overline{WDO}$  goes high as soon as  $V_{CC}$  exceeds the reset threshold.  $\overline{WDO}$  may be used to generate a reset pulse by connecting it to the  $\overline{MR}$  input.

#### 3.5 Power-fail input/output

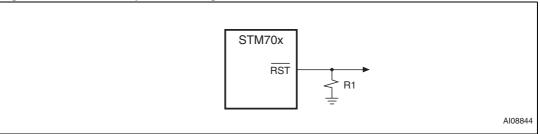
The power-fail input (PFI) is compared to an internal reference voltage (independent from the  $V_{RST}$  comparator). If PFI is less than the power-fail threshold ( $V_{PFI}$ ), the power-fail output ( $\overline{PFO}$ ) will go low. This function is intended for use as an undervoltage detector to signal a failing power supply. Typically PFI is connected through an external voltage divider (see *Figure 9*) to either the unregulated DC input (if it is available) or the regulated output of the  $V_{CC}$  regulator. The voltage divider can be set up such that the voltage at PFI falls below  $V_{PFI}$  several milliseconds before the regulated  $V_{CC}$  input to the STM70x or the microprocessor drops below the minimum operating voltage.

If the comparator is unused, PFI should be connected to  $V_{SS}$  and  $\overline{PFO}$  left unconnected.  $\overline{PFO}$  may be connected to  $\overline{MR}$  on the STM70x so that a low voltage on PFI will generate a reset output.

### 3.6 Ensuring a valid reset output down to $V_{CC} = 0 \text{ V}$

When  $V_{CC}$  falls below 1 V, the state of the  $\overline{RST}$  output can no longer be guaranteed, and becomes essentially an open circuit. If a high value pulldown resistor is added to the  $\overline{RST}$  pin, the output will be held low during this condition. A resistor value of approximately 100 k $\Omega$  will be large enough to not load the output under operating conditions, but still sufficient to pull  $\overline{RST}$  to ground during this low voltage condition (see *Figure 10*).

Figure 10. Reset output valid to ground circuit



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### 3.7 Interfacing to microprocessors with bi-directional reset pins

Microprocessors with bi-directional reset pins can contend with the STM70x reset output. For example, if the reset output is driven high and the micro wants to pull it low, signal contention will result. To prevent this from occurring, connect a  $4.7 k\Omega$  resistor between the reset output and the micro's reset I/O as in *Figure 11*.

Buffered reset to other system components

VCC
STM70x
RST

4.7 kΩ
RST
GND

GND

GND

GND

Figure 11. Interfacing to microprocessors with bi-directional reset I/O

## 4 Typical operating characteristics

Typical values are at  $T_A = 25$  °C.

Figure 12. Supply current vs. temperature (no load)

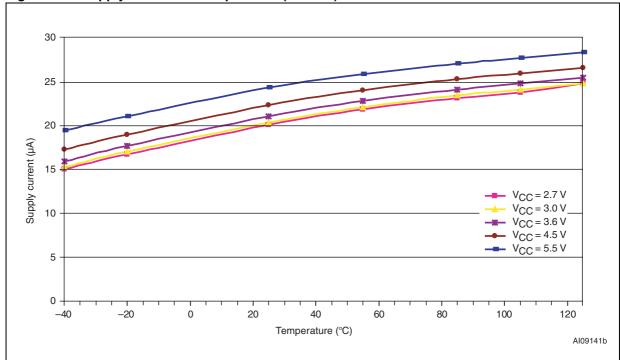


Figure 13.  $V_{PFI}$  threshold vs. temperature

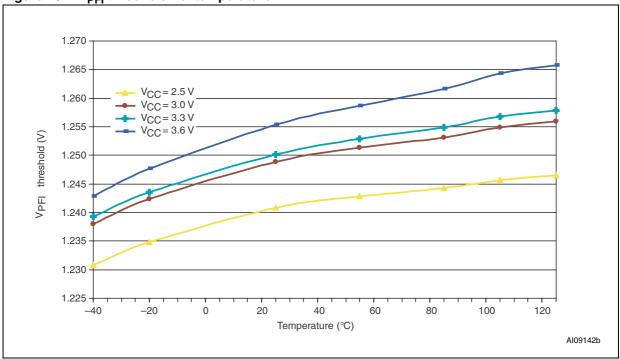


Figure 14. Reset comparator propagation delay vs. temperature

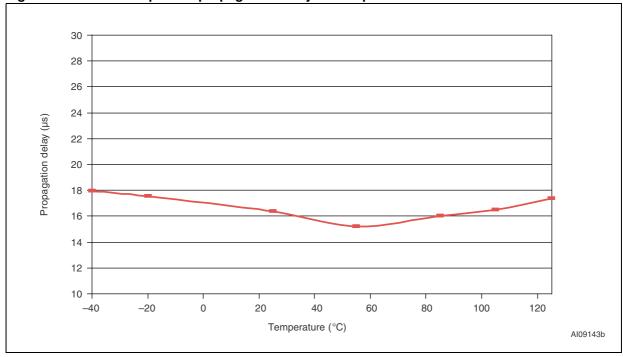


Figure 15. Power-up t<sub>rec</sub> vs. temperature

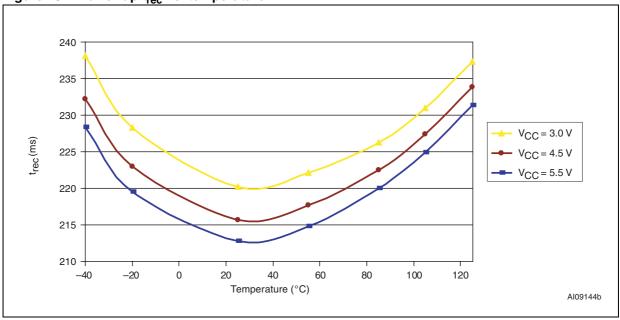


Figure 16. Normalized reset threshold vs. temperature

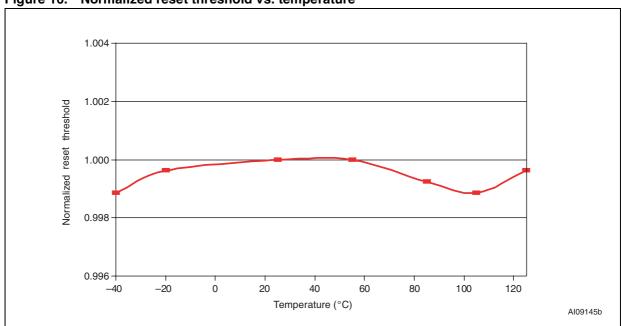


Figure 17. Watchdog timeout period vs. temperature

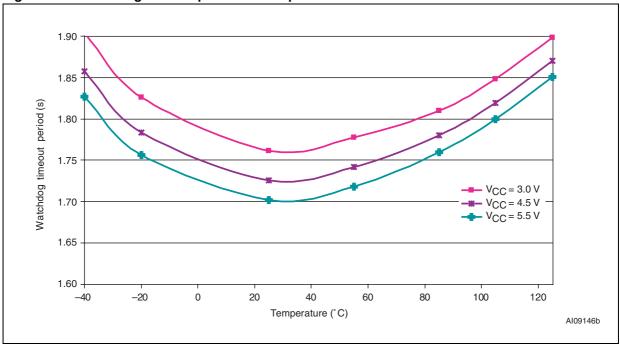


Figure 18. PFI to PFO propagation delay vs. temperature

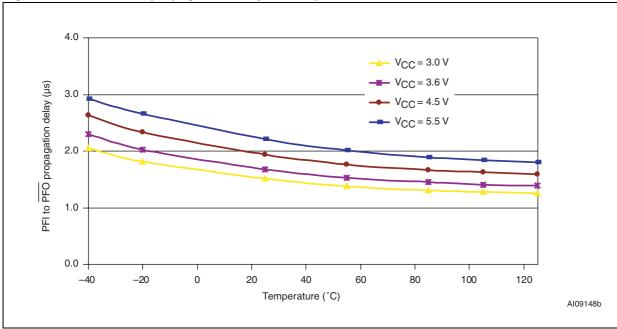


Figure 19. Output voltage vs. load current ( $V_{CC} = 5 \text{ V}$ ;  $T_A = 25 ^{\circ}\text{C}$ )

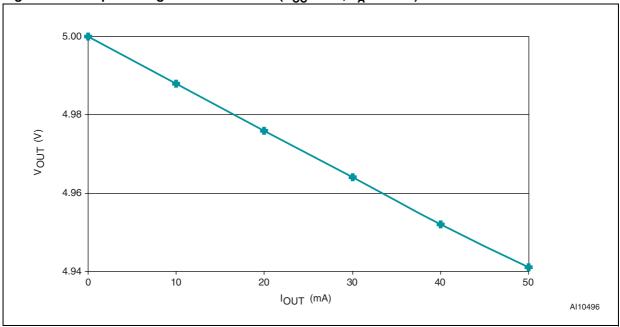


Figure 20. RST output voltage vs. supply voltage

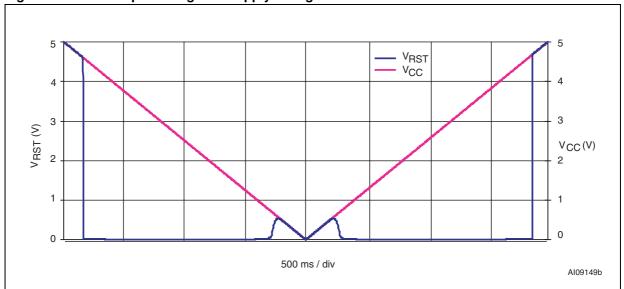


Figure 21. RST output voltage vs. supply voltage

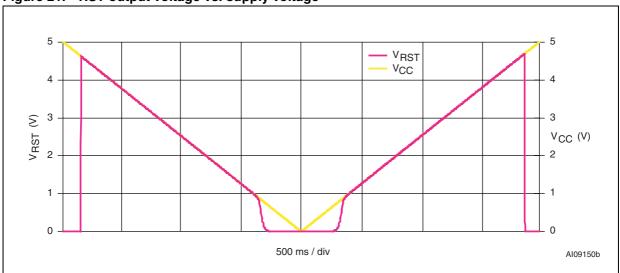
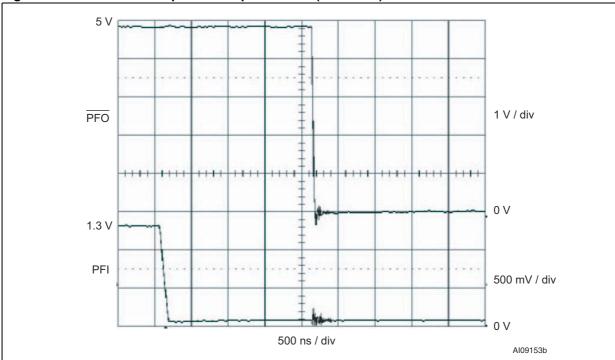


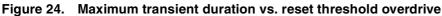
Figure 22. Power-fail comparator response time (assertion)

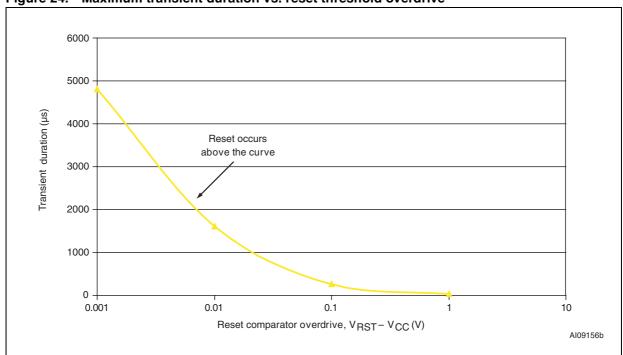


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5 V PFO 1 V / div 0 V 1.3 V PFI 500 mV / div 0 V 500 ns / div

Figure 23. Power-fail comparator response time (de-assertion)





## 5 Maximum ratings

Stressing the device above the rating listed in the *Table 4: Absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in *Table 5: Operating and AC measurement conditions* of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
T <sub>STG</sub>	Storage temperature (V <sub>CC</sub> off)	-55 to 150	°C
T <sub>SLD</sub> <sup>(1)</sup>	Lead solder temperature for 10 seconds	260	°C
V <sub>IO</sub> <sup>(2)</sup>	Input or output voltage	-0.3 to V <sub>CC</sub> +0.3	V
V <sub>CC</sub>	Supply voltage	-0.3 to 7.0	V
Io	Output current	20	mA
P <sub>D</sub>	Power dissipation	320	mW

<sup>1.</sup> Reflow at peak temperature of 260 °C. The time above 255 °C must not exceed 30 seconds.

<sup>2.</sup> Negative undershoot of -1.5 V for up to 10 ns or positive overshoot of  $V_{CC}$  + 1.5 V for up to 10 ns is allowable on the WDI and  $\overline{MR}$  input pins.

### 6 DC and AC parameters

This section summarizes the operating measurement conditions, and the DC and AC characteristics of the device. The parameters in *Table 6: DC and AC characteristics* are derived from tests performed under the measurement conditions summarized in *Table 5: Operating and AC measurement conditions*. Designers should check that the operating conditions in their circuit match the operating conditions when relying on the quoted parameters.

Table 5. Operating and AC measurement conditions

Parameter	STM70x	Unit
V <sub>CC</sub> supply voltage	1.0 to 5.5	V
Ambient operating temperature (T <sub>A</sub> )	-40 to 85	°C
Input rise and fall times	≤5	ns
Input pulse voltages	0.2 to 0.8 V <sub>CC</sub>	V
Input and output timing ref. voltages	0.3 to 0.7 V <sub>CC</sub>	V

Figure 25. AC testing input/output waveforms

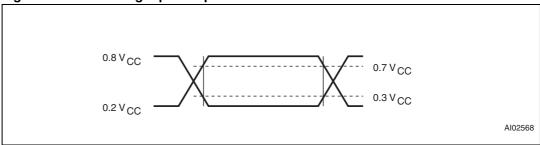


Figure 26. Power-fail comparator waveform

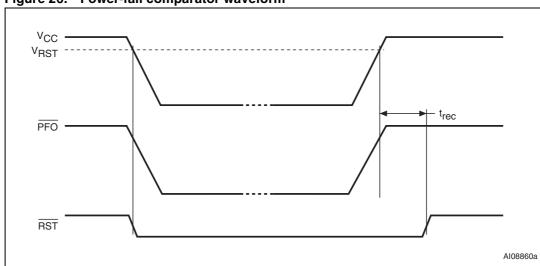
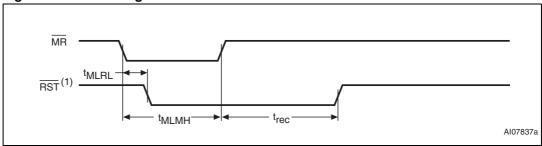


Figure 27. MR timing waveform



1. RST for STM706P and STM708T/S/R.

Figure 28. Watchdog timing (STM706T/S/R and STM706P)

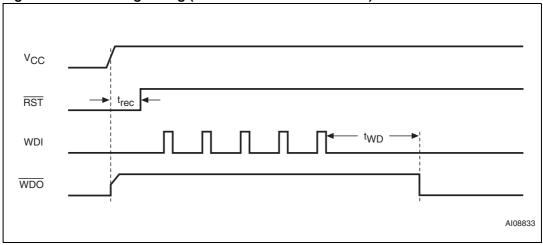


Table 6. DC and AC characteristics

Symbol	Description	Test condition <sup>(1)</sup>	Min.	Тур.	Max.	Unit
$V_{CC}$	Operating voltage		1.2 <sup>(2)</sup>		5.5	٧
I <sub>CC</sub>	V supply surrent	V <sub>CC</sub> < 3.6 V		35	50	μΑ
ICC	V <sub>CC</sub> supply current	V <sub>CC</sub> < 5.5 V		40	60	μΑ
	Input leakage current (WDI)	0 V < V <sub>IN</sub> < V <sub>CC</sub>	-1		+1	μΑ
I <sub>LI</sub>	Input leakage current (PFI)	0 V < V <sub>IN</sub> < V <sub>CC</sub>	-25	2	+25	nA
	Input leakage current	V <sub>RST</sub> (max.) < V <sub>CC</sub> < 3.6 V	25	80	250	μΑ
	(MR)	4.5 V < V <sub>CC</sub> < 5.5 V	75	125	300	μΑ
	Input high voltage (MR)	4.5 V < V <sub>CC</sub> < 5.5 V	2.0			٧
$V_{IH}$	input flight voltage (Mh)	V <sub>RST</sub> (max.) < V <sub>CC</sub> < 3.6 V	0.7 V <sub>CC</sub>			٧
V <sub>IH</sub>	Input high voltage (WDI)	V <sub>RST</sub> (max.) < V <sub>CC</sub> < 5.5 V	0.7 V <sub>CC</sub>			٧
V <sub>IL</sub>	Input low voltage (MR)	4.5 V < V <sub>CC</sub> < 5.5 V			0.8	٧
VIL	input low voltage (IVIA)	V <sub>RST</sub> (max.) < V <sub>CC</sub> < 3.6 V			0.6	٧
V <sub>IL</sub>	Input low voltage (WDI)	V <sub>RST</sub> (max.) < V <sub>CC</sub> < 5.5 V			0.3 V <sub>CC</sub>	٧
V <sub>OL</sub>	Output low voltage (PFO, RST, RST, WDO)	$V_{CC} = V_{RST}$ (max.), $I_{SINK} = 3.2$ mA			0.3	V
V	Output law valtage (DST)	$I_{SINK} = 50 \mu A, V_{CC} = 1.0 V,$ $T_{A} = 0 ^{\circ}C \text{ to } 85 ^{\circ}C$			0.3	V
V <sub>OL</sub>	Output low voltage (RST)	I <sub>SINK</sub> = 100 μA, V <sub>CC</sub> = 1.2 V			0.3	V
V <sub>OH</sub>	Output high voltage (RST, RST, WDO)	I <sub>SOURCE</sub> = 1 mA, V <sub>CC</sub> = V <sub>RST</sub> (max.)	2.4			V
	Output high voltage (PFO)	I <sub>SOURCE</sub> = 75 μA, V <sub>CC</sub> = V <sub>RST</sub> (max.)	0.8 V <sub>CC</sub>			V
Power-fai	l comparator					
V <sub>PFI</sub>	PFI input threshold	PFI falling (STM70xP/R, $V_{CC} = 3.0 \text{ V}$ ; STM70xS/T, $V_{CC} = 3.3 \text{ V}$ )	1.20	1.25	1.30	V
t <sub>PFD</sub>	PFI to PFO propagation delay			2		μs

Table 6. DC and AC characteristics (continued)

Symbol	Description	Test condition <sup>(1)</sup>	Min.	Тур.	Max.	Unit	
Reset thre	esholds						
		STM706P/70xR	2.55	2.63	2.70	V	
V <sub>RST</sub>	Reset threshold <sup>(3)</sup>	STM70xS	2.85	2.93	3.00	V	
		STM70xT	3.00	3.08	3.15	V	
	Reset threshold hysteresis			20		mV	
t <sub>rec</sub>	RST pulse width	Blank (see <i>Table 9</i> )	140	200	280	ms ms	
	HST pulse width	A <sup>(4)</sup> (see <i>Table 9</i> )	160	200	280		
Push-but	ton reset input						
t <sub>MLMH</sub>	MR pulse width	V <sub>RST</sub> (max.) < V <sub>CC</sub> < 3.6 V	500			ns	
(or t <sub>MR</sub> )	Twit puise width	4.5 V < V <sub>CC</sub> < 5.5 V	150			ns	
t <sub>MLRL</sub>	MR to RST output delay	V <sub>RST</sub> (max.) < V <sub>CC</sub> < 3.6 V			750	ns	
(or t <sub>MRD</sub> )	Wirt to Flor output delay	4.5 V < V <sub>CC</sub> < 5.5 V			250	ns	
Watchdoo	g timer (STM706T/S/R and STM706P)	)					
	Watahdag timaayit mayiad	STM706P/70xR, V <sub>CC</sub> = 3.0 V	1.12	1.60	2.24	s	
t <sub>WD</sub>	Watchdog timeout period	STM70xS/70XT, V <sub>CC</sub> = 3.3 V					
	M/DL pulgo width	4.5 V < V <sub>CC</sub> < 5.5 V	50			ns	
	WDI pulse width	V <sub>RST</sub> (max.) < V <sub>CC</sub> < 3.6 V	100			ns	

<sup>1.</sup> Valid for ambient operating temperature:  $T_A = -40$  to 85 °C;  $V_{CC} = V_{RST}$  (max.) to 5.5 V (except where noted).

<sup>2.</sup>  $V_{CC}$  (min) = 1.0 V for  $T_A$  = 0 °C to +85 °C.

<sup>3.</sup> For  $V_{CC}$  falling.

<sup>4.</sup> STM706P/STM70xR device,  $V_{CC} = 3 \text{ V}$ ; STM706xS/STM70xT device,  $V_{CC} = 3.3 \text{ V}$ .

# 7 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

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A2 D ddd

B E H

A1 \( \alpha \)

SOA

Figure 29. SO8 – 8-lead plastic small outline, 150 mils body width, package mechanical

Note: Drawing is not to scale.

Table 7. SO8 - 8-lead plastic small outline, 150 mils body width, package mechanical data

		Dimensions						
Symbol		mm			inches			
	Тур.	Min.	Max.	Тур.	Min.	Max.		
А	_	1.35	1.75	_	0.053	0.069		
A1	_	0.10	0.25	_	0.004	0.010		
В	_	0.33	0.51	_	0.013	0.020		
С	_	0.19	0.25	_	0.007	0.010		
D	_	4.80	5.00	_	0.189	0.197		
ddd	_	_	0.10	_	_	0.004		
Е	_	3.80	4.00	_	0.150	0.157		
е	1.27	_	_	0.050	_	_		
Н	_	5.80	6.20	_	0.228	0.244		
h	_	0.25	0.50	_	0.010	0.020		
L	_	0.40	0.90	_	0.016	0.035		
α	_	0°	8°	_	0°	8°		
N	8	8						

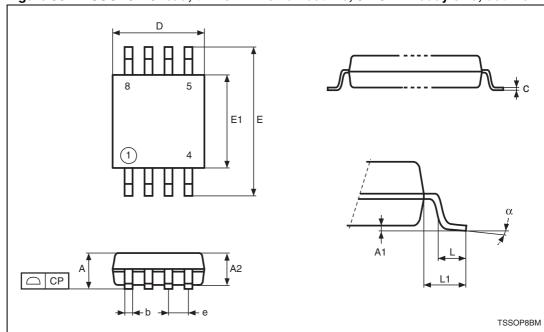


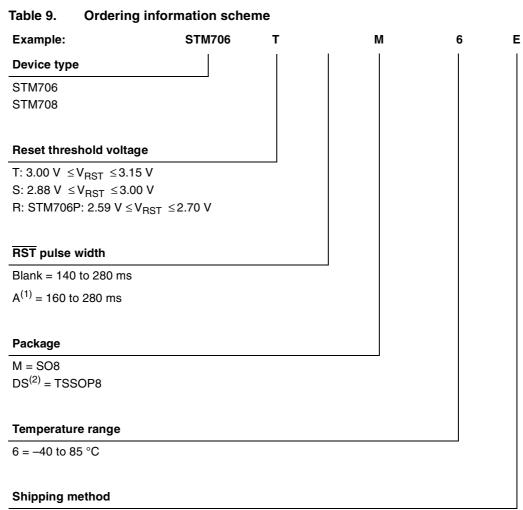
Figure 30. TSSOP8 - 8-lead, thin shrink small outline, 3 x 3 mm body size, outline

Note: Drawing is not to scale.

Table 8. TSSOP8 - 8-lead, thin shrink small outline, 3 x 3 mm body size, mechanical data

	Dimensions						
Symbol		mm		inches			
	Тур.	Min.	Max.	Тур.	Min.	Max.	
Α	_	_	1.10	_	_	0.043	
A1	_	0.05	0.15	_	0.002	0.006	
A2	0.85	0.75	0.95	0.034	0.030	0.037	
b	_	0.25	0.40	_	0.010	0.016	
С	_	0.13	0.23	_	0.005	0.009	
СР	_	_	0.10	_	_	0.004	
D	3.00	2.90	3.10	0.118	0.114	0.122	
е	0.65	_	_	0.026	_	_	
E	4.90	4.65	5.15	0.193	0.183	0.203	
E1	3.00	2.90	3.10	0.118	0.114	0.122	
L	0.55	0.40	0.70	0.022	0.016	0.030	
L1	0.95	_	_	0.037	_	_	
α	_	0°	6°	_	0°	6°	
N	8	8					

## 8 Part numbering



E = ECOPACK® packages, tubes

F = ECOPACK® packages, tape and reel

- 1. Available in SO8 (M) package only.
- 2. Contact local ST sales office for availability.

For other options, or for more information on any aspect of this device, please contact the ST sales office nearest you.

Table 10. Marking description

Part number	Reset threshold	Package	Topside marking
STM706P	2.63 V	SO8	- 706P
		TSSOP8	
STM706T	3.08 V	SO8	- 706T
		TSSOP8	
STM706S	2.93 V	SO8	- 706S
		TSSOP8	
STM706R	2.63 V	SO8	- 706R
		TSSOP8	
STM708T	3.08 V	SO8	- 708T
		TSSOP8	
STM708S	2.93 V	SO8	- 708S
		TSSOP8	
STM708R	2.63 V	SO8	- 708R
		TSSOP8	

# 9 Revision history

Table 11. Document revision history

Date	Revision	Changes	
Oct-2003	1	Initial release.	
12-Dec-2003	2	Reformatted; update characteristics ( <i>Figure 2</i> , <i>3</i> , <i>8</i> to <i>10</i> , <i>27</i> to <i>29</i> ; <i>Table 6</i> to <i>9</i> ).	
16-Jan-2004	2.1	Add Typical operating characteristics (Figure 13, to 19, 21, to 25).	
09-Apr-2004	3	Reformatted; update characteristics (Figure 15, 19, 21, 22, 25; Table 8).	
25-May-2004	4	Update characteristics (Table 3, Table 6).	
02-Jul-2004	5	Datasheet promoted; waveform corrected (Table 27).	
21-Sep-2004	6	Clarify root part numbers; (Figure 2, to 10, 29; Table 1, 3, 6, 9).	
25-Feb-2005	7	Update typical characteristics (Figure 13 to 25).	
02-Nov-2009	8	Updated Table 1, Table 3, Table 4, Table 6, Table 9, Section 2.3, Section 2.7, text in Section 7; reformatted document.	
30-Apr-2010	9	Updated <i>Table 4</i> , corrected typo in <i>Table 2</i> , <i>Section 2.3</i> , <i>Section 3</i> , <i>Section 5</i> and <i>Section 6</i> , <i>Figure 17</i> , <i>Table 7</i> and <i>Table 8</i> .	
06-Aug-2010	10	Updated Features, Section 4: Typical operating characteristics; Table 9.	
06-Sep-2011	11	Updated Section 2.7, Section 5 and Disclaimer, minor typo modifications throughout the document.	
21-Aug-2012	12	Added <i>Applications</i> , updated <i>Section 2.2</i> and <i>Section 2.3</i> , added note to <i>Section 3.3</i> , added cross-references in <i>Section 5</i> and <i>Section 6</i> , minor text corrections throughout document.	

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